D OR N PACKAGE (TOP VIEW)

NC

IN- Π 4

IN+ [

REF

V<sub>CC</sub>-

CURR LIM [

CURR SENS [] 3

SLVS057D - AUGUST 1972 - REVISED JULY 1999

**I**I NC 14

12 [] V<sub>CC+</sub> 

9 🛛 V<sub>Z</sub> 8 [] NC

11

10

13 | FREQ COMP

**NOUTPUT** 

- 150-mA Load Current Without External **Power Transistor**
- **Adjustable Current-Limiting Capability**
- Input Voltages up to 40 V
- Output Adjustable From 2 V to 37 V
- Direct Replacement for Fairchild µA723C

#### description

The µA723 is a precision integrated-circuit voltage regulator, featuring high ripple rejection,

excellent input and load regulation, excellent temperature stability, and low standby current. The circuit consists of a temperature-compensated reference-voltage amplifier, an error amplifier, a 150-mA output transistor, and an adjustable-output current limiter.

The μA723 is designed for use in positive or negative power supplies as a series, shunt, switching, or floating regulator. For output currents exceeding 150 mA, additional pass elements can be connected as shown in Figures 4 and 5.

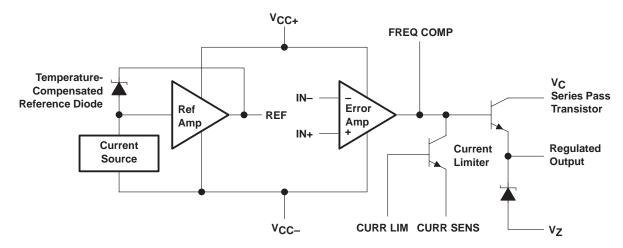
The μA723C is characterized for operation from 0°C to 70°C.

#### **AVAILABLE OPTIONS**

	PACKAGE	CHIP	
TA	PLASTIC DIP (N)	SMALL OUTLINE (D)	FORM (Y)
0°C to 70°C	μΑ723CN	μΑ723CD	μΑ723Y

The D package is available taped and reeled. Add the suffix R to the device type (e.g., µA723CDR). Chip forms are tested at 25°C.

#### functional block diagram

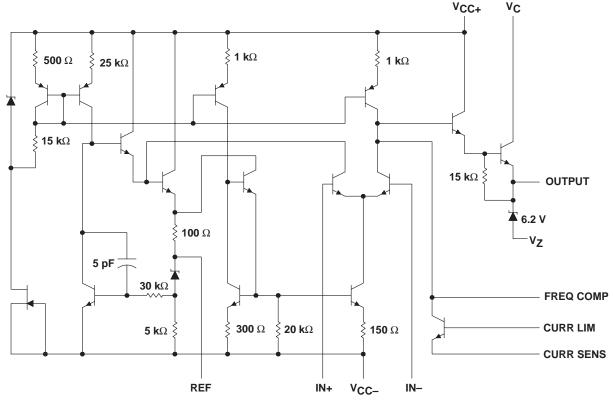




Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



#### schematic



Resistor and capacitor values shown are nominal.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Peak voltage from $V_{CC+}$ to $V_{CC-}$ ( $t_w \le 50$ ms)	50 V
Continuous voltage from V <sub>CC+</sub> to V <sub>CC-</sub>	40 V
Input-to-output voltage differential	40 V
Differential input voltage to error amplifier	±5 V
Voltage between noninverting input and V <sub>CC</sub>	8 V
Current from V <sub>Z</sub>	25 mA
Current from REF	15 mA
Package thermal impedance, θ <sub>JA</sub> (see Notes 1 and 2): D package	86°C/W
N package	101°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D or N package	260°C
Storage temperature range, T <sub>stg</sub> 6	5°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can impact reliability.
  - 2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.



### recommended operating conditions

		MIN	MAX	UNIT
Input voltage, V <sub>I</sub>		9.5	40	V
Output voltage, VO		2	37	V
Input-to-output voltage differential, V <sub>C</sub> – V <sub>O</sub>		3	38	V
Output current, IO			150	mA
Operating free-air temperature range, TA	μΑ723C	0	70	°C

### electrical characteristics at specified free-air temperature (see Notes 3 and 4)

PARAMETER	TEST CONDIT	TEST CONDITIONS			μ <b>Α723C</b>			
PARAMETER	TEST CONDIT	TA	MIN	TYP	MAX	UNIT		
	$V_{I} = 12 \text{ V to } V_{I} = 15 \text{ V}$		25°C		0.1	1		
Input regulation	$V_{I} = 12 \text{ V to } V_{I} = 40 \text{ V}$		25°C		1	5	mV/V	
	$V_{I} = 12 \text{ V to } V_{I} = 15 \text{ V}$		0°C to 70°C			3		
Pipple rejection	f = 50 Hz to 10 kHz,	$C_{ref} = 0$	25°C		74		dB	
Ripple rejection	f = 50 Hz to 10 kHz,	$C_{ref} = 5 \mu F$	25°C		86			
Output regulation			25°C		-0.3	-2	-2 mV/V	
Output regulation			0°C to 70°C			-6	IIIV/V	
Reference voltage, V <sub>ref</sub>			25°C	6.8	7.15	7.5	V	
Standby current	V <sub>I</sub> = 30 V,	I <sub>O</sub> = 0	25°C		2.3	4	mA	
Temperature coefficient of output voltage			0°C to 70°C		0.003	0.015	%/°C	
Short-circuit output current	$R_{SC} = 10 \Omega$ ,	VO = 0	25°C		65		mA	
Output poins voltage	BW = 100 Hz to 10 kHz,	C <sub>ref</sub> = 0	25°C		20			
Output noise voltage	BW = 100 Hz to 10 kHz,	C <sub>ref</sub> = 5 μF	25°C		2.5		μV	

NOTES: 3. For all values in this table, the device is connected as shown in Figure 1 with the divider resistance as seen by the error amplifier  $\leq$  10 k $\Omega$ . Unless otherwise specified, V<sub>I</sub> = V<sub>CC+</sub> = V<sub>C</sub> = 12 V, V<sub>CC-</sub> = 0, V<sub>O</sub> = 5 V, I<sub>O</sub> = 1 mA, R<sub>SC</sub> = 0, and C<sub>ref</sub> = 0.

4. Pulse-testing techniques must be used that will maintain the junction temperature as close to the ambient temperature as possible.

### electrical characteristics, T<sub>A</sub> = 25°C (see Notes 3 and 4)

PARAMETER	TEST CONDIT	μ <b>Α723Υ</b>			UNIT		
PARAMETER	TEST CONDIT	MIN	TYP	MAX	UNIT		
Input regulation	V <sub>I</sub> = 12 V to V <sub>I</sub> = 15 V		0.1			mV/V	
Imput regulation	$V_{I} = 12 \text{ V to } V_{I} = 40 \text{ V}$						
Biople rejection	f = 50 Hz to 10 kHz,	$C_{ref} = 0$	74		dB		
Ripple rejection	f = 50 Hz to 10 kHz,	C <sub>ref</sub> = 5 μF		86		ub	
Output regulation				-0.3		mV/V	
Reference voltage, V <sub>ref</sub>				7.15		V	
Standby current	V <sub>I</sub> = 30 V,	IO = 0		2.3		mA	
Short-circuit output current	$R_{SC} = 10 \Omega$	VO = 0		65		mA	
Output noise voltage	BW = 100 Hz to 10 kHz, $C_{ref} = 0$			20		\	
Output hoise voltage	BW = 100 Hz to 10 kHz,	C <sub>ref</sub> = 5 μF		2.5		μV	

NOTES: 3. For all values in this table, the device is connected as shown in Figure 1 with the divider resistance as seen by the error amplifier  $\leq$  10 k $\Omega$ . Unless otherwise specified, V<sub>I</sub> = V<sub>CC+</sub> = V<sub>C</sub> = 12 V, V<sub>CC-</sub> = 0, V<sub>O</sub> = 5 V, I<sub>O</sub> = 1 mA, R<sub>SC</sub> = 0, and C<sub>ref</sub> = 0.

4. Pulse-testing techniques must be used that will maintain the junction temperature as close to the ambient temperature as possible.

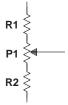


Table 1. Resistor Values ( $k\Omega$ ) for Standard Output Voltages

OUTPUT VOLTAGE	APPLICABLE FIGURES	FIXED C	OUTPUT %	OUTPUT ADJUSTABLE ±10% (SEE NOTE 6)		
(V)	(SEE NOTE 5)	R1 (kΩ)	R2 (kΩ)	R1 (kΩ)	P1 (kΩ)	P2 (kΩ)
3.0	1, 5, 6, 9, 11, 12 (4)	4.12	3.01	1.8	0.5	1.2
3.6	1, 5, 6, 9, 11, 12 (4)	3.57	3.65	1.5	0.5	1.5
5.0	1, 5, 6, 9, 11, 12 (4)	2.15	4.99	0.75	0.5	2.2
6.0	1, 5, 6, 9, 11, 12 (4)	1.15	6.04	0.5	0.5	2.7
9.0	2, 4, (5, 6, 9, 12)	1.87	7.15	0.75	1.0	2.7
12	2, 4, (5, 6, 9, 12)	4.87	7.15	2.0	1.0	3.0
15	2, 4, (5, 6, 9, 12)	7.87	7.15	3.3	1.0	3.0
28	2, 4, (5, 6, 9, 12)	21.0	7.15	5.6	1.0	2.0
45	7	3.57	48.7	2.2	10	39
75	7	3.57	78.7	2.2	10	68
100	7	3.57	105	2.2	10	91
250	7	3.57	255	2.2	10	240
-6 (see Note 7)	3, 10	3.57	2.43	1.2	0.5	0.75
-9	3, 10	3.48	5.36	1.2	0.5	2.0
-12	3, 10	3.57	8.45	1.2	0.5	3.3
-15	3, 10	3.57	11.5	1.2	0.5	4.3
-28	3, 10	3.57	24.3	1.2	0.5	10
-45	8	3.57	41.2	2.2	10	33
-100	8	3.57	95.3	2.2	10	91
-250	8	3.57	249	2.2	10	240

NOTES: 5. The R1/R2 divider can be across either V<sub>O</sub> or V<sub>(ref)</sub>. If the divider is across V<sub>(ref)</sub>, use the figure numbers without parentheses. If the divider is across V<sub>O</sub> use the figure numbers in parentheses

VO, use the figure numbers in parentheses.
To make the voltage adjustable, the R1/R2 divider shown in the figures must be replaced by the divider shown below.



#### **Adjustable Output Circuit**

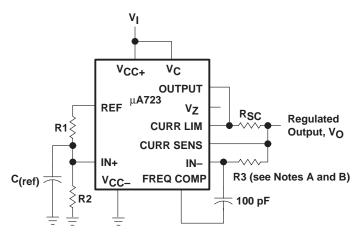
7. For Figures 3, 8, and 10, the device requires a minimum of 9 V between  $V_{CC+}$  and  $V_{CC-}$  when  $V_O$  is equal to or more positive than -9 V.



**Table 2. Formulas for Intermediate Output Voltages** 

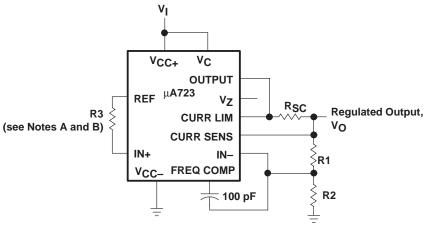
OUTPUTS FROM 2 V TO 7 V SEE FIGURES 1, 5, 6, 9, 11, 12 (4) AND NOTE 5	OUTPUTS FROM 4 V TO 250 V SEE FIGURE 7 AND NOTE 5	CURRENT LIMITING
$V_{O} = V_{(ref)} \times \frac{R2}{R1 + R2}$	$V_{O} = \frac{V_{(ref)}}{2} \times \frac{R2 - R1}{R1}$ R3 = R4	$I_{(limit)} \approx \frac{0.65 \text{ V}}{R_{SC}}$
OUTPUTS FROM 7 V TO 37 V SEE FIGURES 2, 4, (5, 6, 9, 11, 12) AND NOTE 5	OUTPUTS FROM -6 V TO -250 V SEE FIGURES 3, 8, 10 AND NOTES 5 AND 7	FOLDBACK CURRENT LIMITING SEE FIGURE 6
$V_{O} = V_{(ref)} \times \frac{R1 + R2}{R2}$	$V_{O} = -\frac{V_{(ref)}}{2} \times \frac{R1 + R2}{R1}$ $R3 = R4$	$I_{(knee)} \approx \frac{V_{O}R3 + (R3 + R4) \ 0.65 \ V}{R_{SC}R4}$ $I_{OS} \approx \frac{0.65 \ V}{R_{SC}} \times \frac{R3 + R4}{R4}$

- NOTES: 5. The R1/R2 divider can be across either VO or V(ref). If the divider is across V(ref), use figure numbers without parentheses. If the divider is across  $V_0$ , use the figure numbers in parentheses.
  - 7. For Figures 3, 8, and 10, the device requires a minimum of 9 V between V<sub>CC+</sub> and V<sub>CC-</sub> when V<sub>O</sub> is equal to or more positive than



NOTES: A. R3 =  $\frac{R1 \times R2}{R1 + R2}$  for a minimum  $\alpha_{V_0}$  B. R3 can be eliminated for minimum component count. Use direct connection (i.e., R<sub>3</sub> = 0).

Figure 1. Basic Low-Voltage Regulator (V<sub>O</sub> = 2 V to 7 V)



NOTES: A. R3 =  $\frac{R1 \times R2}{R1 + R2}$  for a minimum  $\alpha_{V_0}$ B. R3 can be eliminated for minimum component count. Use direct connection (i.e., R<sub>3</sub> = 0).

Figure 2. Basic High-Voltage Regulator ( $V_0 = 7 \text{ V to } 37 \text{ V}$ )

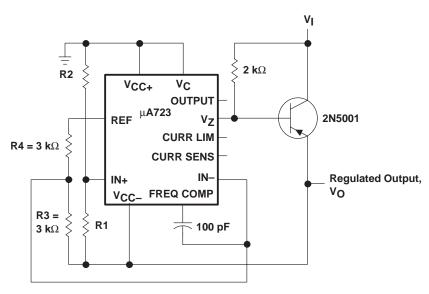


Figure 3. Negative-Voltage Regulator

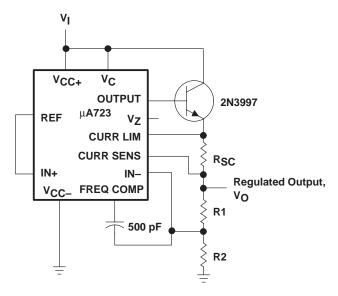


Figure 4. Positive-Voltage Regulator (External npn Pass Transistor)

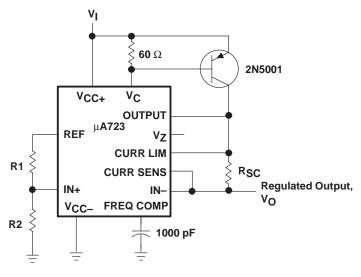


Figure 5. Positive-Voltage Regulator (External pnp Pass Transistor)

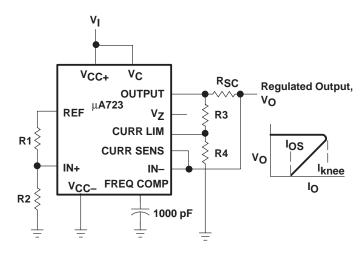


Figure 6. Foldback Current Limiting

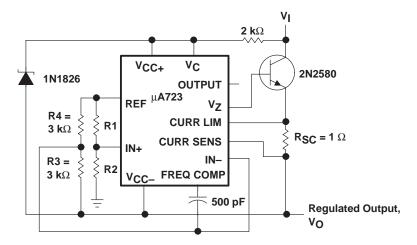


Figure 7. Positive Floating Regulator

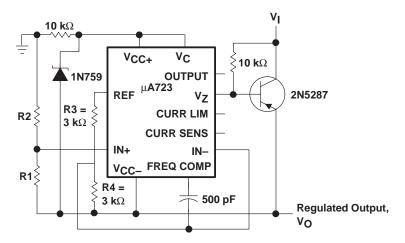
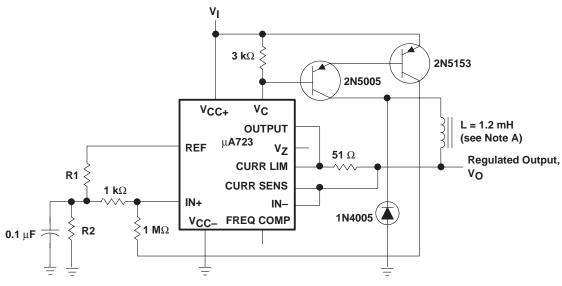
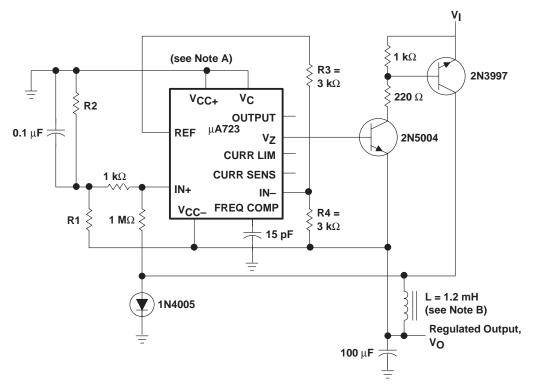


Figure 8. Negative Floating Regulator



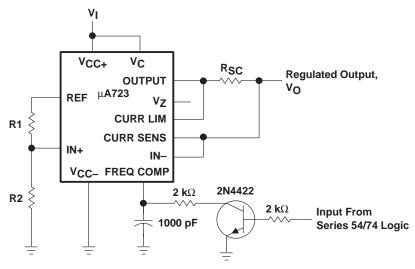
NOTE A: Lis 40 turns of No. 20 enameled copper wire wound on Ferroxcube P36/22-3B7 potted core, or equivalent, with a 0.009-inch air gap.

Figure 9. Positive Switching Regulator



- NOTES: A. The device requires a minimum of 9 V between  $V_{CC+}$  and  $V_{CC-}$  when  $V_O$  is equal to or more positive than -9 V.
  - B. L is 40 turns of No. 20 enameled copper wire wound on Ferroxcube P36/22-3B7 potted core, or equivalent, with a 0.009-inch air gap.

Figure 10. Negative Switching Regulator



NOTE A: A current-limiting transistor can be used for shutdown if current limiting is not required.

Figure 11. Remote Shutdown Regulator With Current Limiting



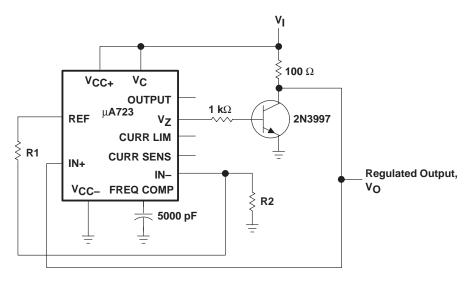


Figure 12. Shunt Regulator





i.com 11-Feb-2005

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
UA723CD	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
UA723CDR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
UA723CJ	OBSOLETE	CDIP	J	14		None	Call TI	Call TI
UA723CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
UA723CNSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# D (R-PDSO-G14)

## PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated

This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.